

L Number	Hits	Search Text	DB	Time stamp
-	38983	c23c016\$.ipc.	JPO; DERWENT	2002/09/23 13:20
-	660865	h01l021\$.ipc.	JPO; DERWENT	2002/05/07 13:21
-	35	118/719.ccls. and ((dope doping doped) with diffus\$3)	USPAT; US-PGPUB	2002/09/23 12:46
-	0	20020046705.URPN.	USPAT	2002/09/23 11:52
-	1	"6319553"	USPAT; US-PGPUB	2002/09/23 12:31
-	1	3805734.URPN.	USPAT	2002/09/23 12:22
-	4	("3441000" "3492969" "3526205" "3578495").PN.	USPAT	2002/09/23 12:26
-	16	c23c016\$.ipc. and ((dop\$3) and (diffus\$3) and heat\$3 and (region chamber area))	EPO; JPO; DERWENT	2002/09/23 12:39
-	1	("5217501").PN.	USPAT; US-PGPUB	2002/09/23 12:40
-	7	c23c016\$.ipc. and ((dop\$3) and (diffus\$3) and heat\$3 and (separate different second))	EPO; JPO; DERWENT	2002/09/23 12:42
-	81	118/719.ccls. and (heat\$3 with diffus\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/23 14:55
-	10	118/719.ccls. and ((heat\$3 with diffus\$3) same dop\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/23 16:12
-	0	20020046705.URPN.	USPAT	2002/09/23 13:23
-	10	5445676.URPN.	USPAT	2002/09/23 14:11
-	48	c23c016\$.ipc. and ((heat\$3 with diffus\$3) same dop\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/23 14:50
-	5	(("5820679") or ("6056849") or ("6207005") or ("2001007244") or ("6319553") or ("6147377")).PN.	USPAT; US-PGPUB	2002/09/23 14:50
-	78	c23c016\$.ipc. and ((heat\$3 same diffus\$3) same dop\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/23 14:54
-	11	c23c016\$.ipc. and ((heat\$3 with diffus\$3) same dop\$3)	EPO; JPO; DERWENT	2002/09/23 14:51
-	17	c23c016\$.ipc. and ((heat\$3 same diffus\$3) same dop\$3)	EPO; JPO; DERWENT	2002/09/23 14:51
-	199	c23c016\$.ipc. and (heat\$3 same dop\$3)	EPO; JPO; DERWENT	2002/09/23 15:07
-	40	118/719.ccls. and (heat\$3 with dop\$3\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/23 14:56
-	40	118/719.ccls. and (heat\$3 with dop\$3\$3)	USPAT; US-PGPUB	2002/09/23 14:57
-	29	c23c016\$.ipc. and (heat\$3 and dop\$3 and diffus\$3)	EPO; JPO; DERWENT	2002/09/23 15:13
-	3	118/719.ccls. and (("ald" "atomic layer deposition") and dop\$3)	USPAT; US-PGPUB	2002/09/23 15:14
-	1	c23c016\$.ipc. and (("ald" "atomic layer deposition") and dop\$3)	EPO; JPO; DERWENT	2002/09/23 15:47
-	64	c23c016\$.ipc. and (("ald" "atomic layer deposition"))	EPO; JPO; DERWENT	2002/09/23 16:01
-	6	(("ald" "atomic layer deposition") and dop\$3)	EPO; JPO; DERWENT	2002/09/23 15:47
-	9	118/719.ccls. and (("ald" "atomic layer deposition"))	USPAT; US-PGPUB	2002/09/23 15:57
-	0	20010007244.URPN.	USPAT	2002/09/23 15:49
-	19	118/719.ccls. and (("ald" "atomic layer deposition" "ale" "atomic layer epitaxy"))	USPAT; US-PGPUB	2002/09/23 16:04

-	15	118/719.ccls. and (("ale" "atomic layer epitaxy"))	USPAT; US-PGPUB	2002/09/23 16:01
-	6	118/719.ccls. and (("ale" "atomic layer epitaxy") and dop\$3)	USPAT; US-PGPUB	2002/09/23 16:02
-	128	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) and (dop\$3 same diffus\$3)	USPAT; US-PGPUB	2002/09/23 16:09
-	1	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) and (dop\$3 same diffus\$3)	EPO; JPO; DERWENT	2002/09/23 16:05
-	3	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) same (dop\$3 with diffus\$3)	USPAT; US-PGPUB	2002/09/23 16:07
-	12	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) same dop\$3 same diffus\$3	USPAT; US-PGPUB	2002/09/23 16:07
-	2	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) same (dop\$3 with heat\$3)	USPAT; US-PGPUB	2002/09/23 16:10
-	1392	(substrate wafer semiconductor) and ((heat\$3 with diffus\$3) same dop\$3)	EPO; JPO; DERWENT	2002/09/23 16:13
-	3113	(substrate wafer semiconductor) and ((heat\$3 with diffus\$3) same dop\$3)	USPAT; US-PGPUB	2002/09/23 16:14
-	949	(substrate wafer semiconductor) and ((heat\$3 with diffus\$3) with dop\$3)	EPO; JPO; DERWENT	2002/09/23 16:14
-	1454	substrate wafer semiconductor) same((heat\$3 with diffus\$3) with dop\$3	USPAT; US-PGPUB	2002/09/23 16:15
-	820	(substrate wafer semiconductor) same ((heat\$3 with diffus\$3) with dop\$3)	EPO; JPO; DERWENT	2002/09/23 16:14
-	48	118/\$.ccls. and ((substrate wafer semiconductor)with (heat\$3 with diffus\$3) with dop\$3)	USPAT; US-PGPUB	2002/09/23 16:16
-	96	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) and (dop\$3 same heat\$3)	USPAT; US-PGPUB	2002/09/23 16:30
-	23	(("ald" "atomic layer deposition" "ale" "atomic layer epitaxy")) and (dop\$3 same heat\$3 same diffus\$3)	USPAT; US-PGPUB	2002/09/23 16:41
-	0	20020046705.URPN.	USPAT	2002/09/23 16:40
-	5	(("4533410") or ("5281274") or ("5310698") or ("5527733") or ("5793109")).PN.	USPAT; US-PGPUB	2002/09/23 16:43
-	0	("I203 and dop\$3").PN.	USPAT; US-PGPUB	2002/09/23 16:43
-	4	((("4533410") or ("5281274") or ("5310698") or ("5527733") or ("5793109")).PN.) and dop\$3	USPAT; US-PGPUB	2002/09/23 16:43
-	0	5793109.URPN.	USPAT	2002/09/23 16:44
-	0	5793109.URPN.	USPAT	2002/09/23 16:44
-	2	("5399886" "5610410").PN.	USPAT	2002/09/23 16:44
-	0	5793109.URPN.	USPAT	2002/09/23 16:49
-	0	09/570,340	USPAT; US-PGPUB	2002/09/23 17:18
-	1	"09570340"	USPAT; US-PGPUB	2002/09/23 17:58
-	1	("6319653").PN.	USPAT; US-PGPUB	2002/09/23 17:58
-	1	("6319553").PN.	USPAT; US-PGPUB	2002/09/23 18:07
-	1	("6143082").PN.	USPAT; US-PGPUB	2002/09/23 18:07
-	27	(US-6207005-\$ or US-6319553-\$ or US-4976996-\$ or US-3650042-\$ or US-6372083-\$ or US-6079354-\$ or US-4723507-\$ or US-3805734-\$ or US-4820656-\$ or US-5217501-\$ or US-5445676-\$ or US-5199994-\$ or US-6270619-\$ or US-4608943-\$ or US-6042652-\$ or US-5281274-\$ or US-5458688-\$ or US-5935334-\$ or US-6254805-\$ or US-6143082-\$).did. or (US-20020046705-\$ or US-20010004533-\$ or US-20020100418-\$ or US-20010007244-\$).did. or (EP-490727-\$ or JP-2909481-\$ or FR-2818993-\$).did.	USPAT; US-PGPUB; DERWENT	2002/09/23 18:11

	6	((US-6207005-\$ or US-6319553-\$ or US-4976996-\$ or US-3650042-\$ or US-6372083-\$ or US-6079354-\$ or US-4723507-\$ or US-3805734-\$ or US-4820656-\$ or US-5217501-\$ or US-5445676-\$ or US-5199994-\$ or US-6270619-\$ or US-4608943-\$ or US-6042652-\$ or US-5281274-\$ or US-5458688-\$ or US-5935334-\$ or US-6254805-\$ or US-6143082-\$).did. or (US-20020046705-\$ or US-20010004533-\$ or US-20020100418-\$ or US-20010007244-\$).did. or (EP-490727-\$ or JP-2909481-\$ or FR-2818993-\$).did.) and (heat\$3 same atomic) matsuse.in. and atomic	USPAT; US-PGPUB	2002/09/23 18:13
	2		USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/23 18:13
	116	118/719.ccls. and ((heat\$3 thermal\$3 anneal\$3) with diffus\$3)	USPAT; US-PGPUB	2002/09/23 18:53
	429	c23c016\$.ipc. and ((heat\$3 thermal\$3 anneal\$3) with diffus\$3)	EPO; JPO; DERWENT	2002/09/23 18:53
	39	118/719.ccls. and ((heat\$3 thermal\$3 anneal\$3) with diffus\$3) and dop\$3	USPAT; US-PGPUB	2002/09/23 18:54
	21	c23c016\$.ipc. and ((heat\$3 thermal\$3 anneal\$3) with diffus\$3) and dop\$3	EPO; JPO; DERWENT	2002/09/23 18:54
	11	c23c016\$.ipc. and ((thermal\$3 anneal\$3) with diffus\$3) and dop\$3	EPO; JPO; DERWENT	2002/09/23 18:54
	23	118/719.ccls. and ((thermal\$3 anneal\$3) with diffus\$3) and dop\$3	USPAT; US-PGPUB	2002/09/23 19:15
	15	118/\$.ccls. and ((heat\$3 thermal\$3 anneal\$3) same diffus\$3) same dop\$3 same transfer\$3	USPAT; US-PGPUB	2002/09/23 19:16